



# **DW 291**

MULTI WIRE SAW





WORK PIECE DIMENSIONS: MAX. □ 166 MM × 860 MM







## HIGHEST THROUGHPUT WITH THINNEST WIRE



Patented Diamond Wire Management System (DWMS)

High process automation

Low running costs

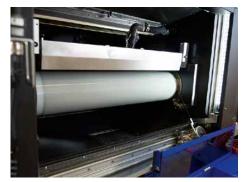
SMART SLICING TECHNOLOGY FOR MONO- AND MULTI-SILICON





#### HIGHLIGHTS DW 291

- M4 capable: Optimized for M4 (161.7 mm) wafer format
- High throughput: 33 m/s wire speed, 10 m/s² acceleration
- DWMS:50 μm wire capability
- Shortest wire path: Only < 1.9 m on one side, easy wire set-up and constant tension
- High capacity: 870 mm web length
- Robust machine: Mineral cast, low vibration, low noise, perfect alignment of all relevant machine parts
- HMI: New HMI on 19" touch screen, production assistant, global process recipes, easy to train, easy to use
- Cleaner wafer: 490 I cutting fluid tank
- Optional MES interface



Long load length for more output



Thin wire for lower cost



Easy operation for higher yield

TECHNICAL DATA	DW 291 FEATURES
Web length [mm]	870
Max. work piece dimensions [mm]	□ 166×860
Wire speed [m/sec]	33
Wire acceleration [m/s²]	10 (< 3.5 s)
Min. wire diameter [µm]	50
Min. wafer thickness [µm]	100
Wire guide roller axis distance [mm]	390
Cutting fluid tank [I]	490
Machine dimensions [L × W × H] [mm]	~ 3700 × 1200 × 2500
Machine weight [kg]	7900

### **GET IN TOUCH WITH US TODAY**

TOGETHER WE WILL FIND A SOLUTION FOR YOUR REQUIREMENTS

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